Power MOSFETs Panasonic

# 2SK3892

## Silicon N-channel power MOSFET

For contactless relay, diving circuit for a solenoid, driving circuit for a motor, control equipment and switching power supply

#### ■ Features

- $\bullet$  Gate-source surrender voltage  $V_{GSS}$  :  $\pm\,30$  guaranteed
- Avalanche energy capacity guaranteed: EAS > 986 mJ
- High-speed switching:  $t_f = 39 \text{ ns}$

### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V <sub>DSS</sub>	200	V	
Gate-source surrender voltage	V <sub>GSS</sub>	±30	V	
Drain current	$I_D$	22	A	
Peak drain current	$I_{DP}$	88	A	
Avalanche energy capability *	EAS	986	mJ	
Drain power dissipation $T_a = 25^{\circ}C$	D	40	W	
	$P_{D}$	2.0	W	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	5 °C √	

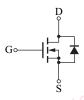
Note) \*: L = 2.67 mH,  $I_L = 22 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ , 1 pulse

### ■ Package

Code

TO-220D-A1

- Pin Name
  - 1: Gate
  - 2: Drain
- 3: Source
- Marking Symbol: K3892
- Internal Connection



#### ■ Electrical Characteristics $T_C = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source surrender voltage	$V_{\rm DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0$	200			V
Drain-source cutoff current	$I_{DSS}$	$V_{DS} = 160 \text{ V}, V_{GS} = 0$			10	μΑ
Gate-source cutoff current	$I_{GSS}$	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$			±1.0	μΑ
Gate threshold voltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 1.0 \text{ mA}$	2.5		4.5	V
Drain-source ON resistance	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 11.0 \text{ A}$		48	62	mΩ
Forward transfer admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 11.0 \text{ A}$	7	15		S
Short-circuit input capacitance (Common source)	C <sub>iss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		3 177		pF
Short-circuit output capacitance (Common source)	C <sub>oss</sub>			456		pF
Reverse transfer capacitance (Common source)	C <sub>rss</sub>			41		pF
Turn-on delay time	t <sub>d(on)</sub>			54		ns
Rise time	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, I_D = 11.0 \text{ A}$		60		ns
Turn-off delay time	t <sub>d(off)</sub>	$R_L = 9.1 \Omega, V_{GS} = 10 V$		194		ns
Fall time	$t_{\rm f}$			39		ns

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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## ■ Electrical Characteristics (continued) $T_C = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Diode forward voltage	V <sub>DSF</sub>	$I_{DR} = 22 \text{ A}, V_{GS} = 0$			-1.5	V
Reverse recovery time	t <sub>rr</sub>	$L = 230 \mu H, V_{DD} = 100 V$		127		ns
Reverse recovery charge	Q <sub>rr</sub>	$I_{DR} = 11.0 \text{ A}, d_i / d_t = 100 \text{ A/}\mu\text{s}$		756		nC
Gate charge load	Qg			50		nC
Gate-source charge	Q <sub>gs</sub>	$V_{DD} = 100 \text{ V}, I_D = 11.0 \text{ A}, V_{GS} = 10 \text{ V}$		12		nC
Gate-drain charge	Q <sub>gd</sub>			18		nC
Thermal resistance (ch-c)	R <sub>th(ch-c)</sub>				3.13	°C/W
Thermal resistance (ch-a)	R <sub>th(ch-a)</sub>				62.5	°C/W

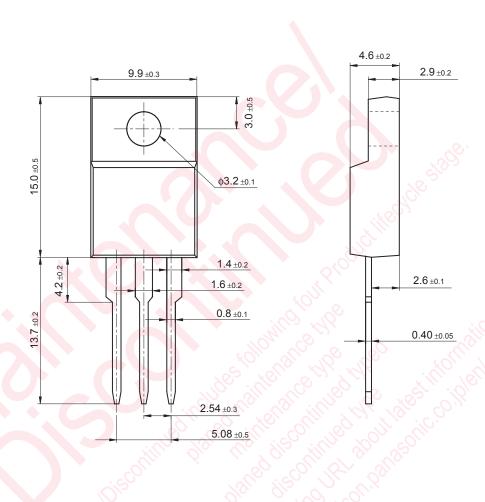
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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TO-220D-A1

Unit: mm



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